

ABSTRACT

Photosensitive Resin Composition and Method for Producing Same

5 The present invention provides: a photosensitive transparent resin composition having excellent thermal shock resistance in the production of products with integrated electronic parts or of solid-state imaging elements that requires a reflow soldering process; and a
10 microplastic lens or an optical-element molded product for liquid crystal polarizing plates that uses said photosensitive transparent resin composition. The photosensitive resin composition contains: 100 parts by mass of a polyorganosiloxane (a) having a polymerizable
15 functional group and prepared according to a method of mixing an alkoxysilane compound represented by the following general formula (1), $R^1_a R^2_b Si(OR^3)_{4-a-b}$ (wherein R^1 , R^2 , R^3 , a, and b are as defined in the Description), with a catalyst and polymerizing the alkoxysilane
20 compound, wherein said polyorganosiloxane (a) includes a structure represented by the following general formula (2), $\equiv Si-O-X-Si \equiv$ (wherein X is as defined in the Description), and the structure of said general formula (2) contains 5 to 60% of the Si atoms contained in said
25 polyorganosiloxane (a); and 0.01 to 30 parts by mass of a photopolymerization initiator (b).

Figure 1